

# **Application Data Sheet**

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Application Information

Application Type::

Subject Matter::

Suggested Classification::

Suggested Group Art Unit::

CD-ROM or CD R?::

Number of CD disks::

Number of copies of CDs::

Sequence Submission::

Computer Readable Form (CRF)?::

Title::

Attorney Docket Number::

Request For Early Publication:: , Request For Non-Publication::

Suggested Drawing Figure::

**Total Drawing Sheets::** 

Small Entity::

Latin Name::

**Variety Denomination Name::** 

Petition Included::

Petition Type::

Licensed US Govt. Agency::

**Contract or Grant Numbers::** 

Secrecy Order in Parent Appl.?::

Utility

Regular

None

No

No

SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE

10873.851US01

No

No

15 No

No

No

Technology Center 210

### **Applicant Information**

**Applicant Authority Type::** 

Inventor

Primary Citizenship Country::

Japan

Status::

**Full Capacity** 

Given Name::

Hiroaki

Middle Name::

Family Name::

Asada

Name Suffix::

City of Residence::

Takatsuki

State or Province of Residence::

Osaka

Country of Residence::

Japan

Street of mailing address::

6-10-1-403, Makami-cho

City of mailing address::

Takatsuki

State or Province of mailing address::

Osaka

Country of mailing address::

Japan

Postal or Zip Code of mailing address:: 569-1121

Correspondence Information

Correspondence Customer Number::

23552

## Representative Information

Representative Customer Number::	23552
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## Foreign Priority Information

Country::	Application Number::	Filing Date::	Priority Claimed::
Japan	2001-083422	03/22/01	Yes

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# Assignee Information

Assignee Name::

Matsushita Electric Industrial Co., Ltd.

Street of mailing address::

1006-banchi, Oaza-Kadoma

City of mailing address::

Kadoma

State or Province of mailing address::

Osaka

Country of mailing address::

Japan

Postal or Zip Code of mailing address:: 571-8501